

### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Built-in strain relief, ideal for automated placement
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed  
250°C/10 seconds at terminals

### Mechanical Data

**Case** : Molded plastic body

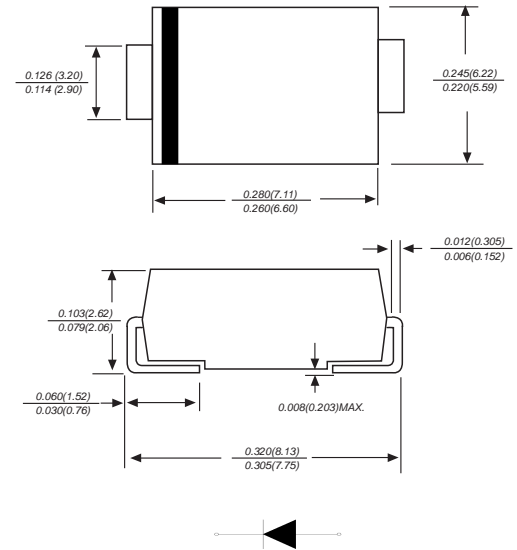
**Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity** : Polarity symbol marking on body

**Mounting Position** : Any

**Weight** : 0.008 ounce, 0.225 grams

**DO-214AB/SMC**  



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS32	SS34	SS36	SS38	SS310	SS315	SS320	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	40	60	80	100	150	200	V
Maximum RMS voltage	$V_{RMS}$	14	28	42	56	70	105	140	V
Maximum DC blocking voltage	$V_{DC}$	20	40	60	80	100	150	200	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	3.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	80.0							A
Maximum instantaneous forward voltage at 3.0A	$V_F$	0.55	0.70	0.85	0.95				V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	$I_R$	0.5 50		0.05 10					mA
Typical thermal resistance	$R_{qJA}$	47.0							$^\circ\text{C}/\text{W}$
Operating junction temperature range	$T_J$	-55 to +150							$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150							$^\circ\text{C}$

**Ratings And Characteristic Curves**

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

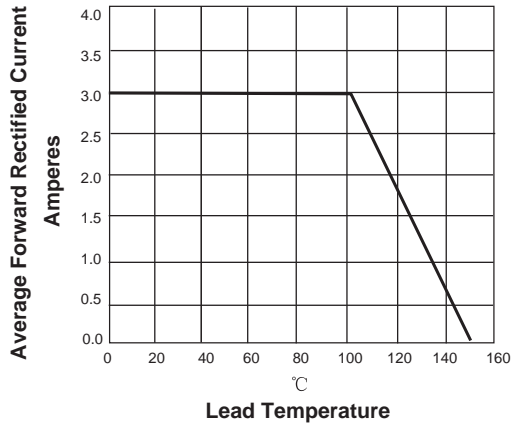


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

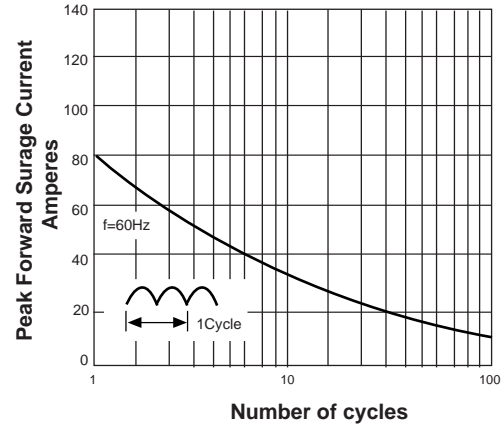


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

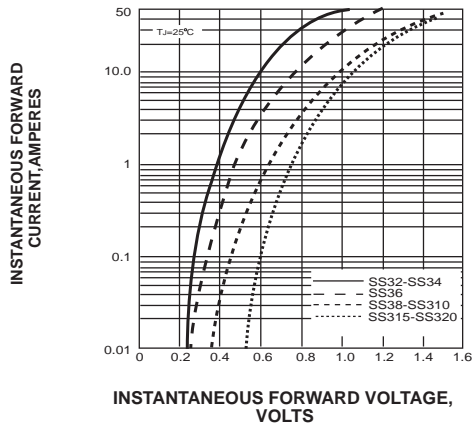
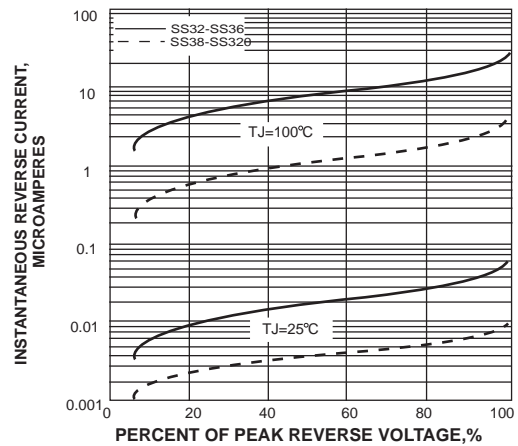
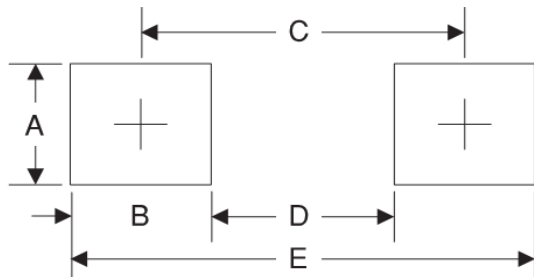


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

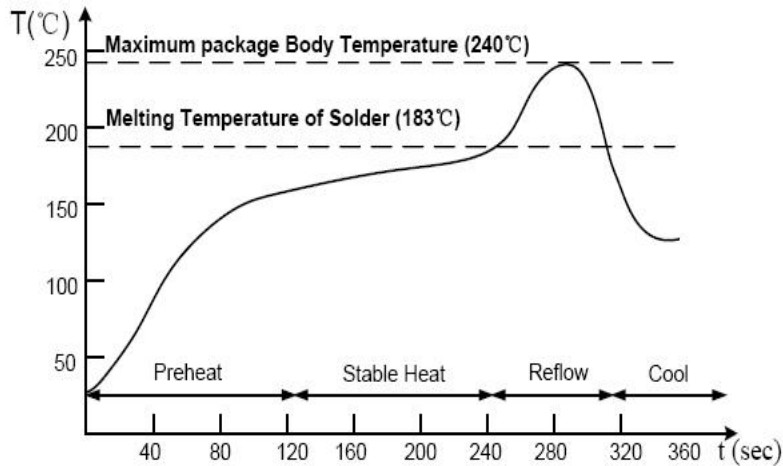


**Suggested Pad Layout**



Symbol	Unit (mm)	Unit (inch)
A	3.30	0.130
B	2.50	0.098
C	6.80	0.268
D	4.40	0.173
E	9.40	0.370

### Suggested Soldering Temperature Profile

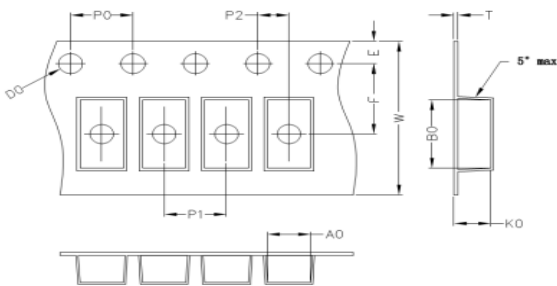


#### Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

### Package Information

#### Carrier Dimension(mm)



A0	B0	K0	D0	E	F
6.05	8.31	2.54	1.55	1.75	7.50
P0	P1	P2	T	W	Tolerance
4.0	8.0	2.0	0.25	16	0.1

#### Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMC	13'	330	3.0	340	6.0	360*360*360	48